

# Ceramic Plate Series CP14-127-10

## Thermoelectric Modules



The Ceramic Plate (CP) Series of Thermoelectric Modules (TEMs) is considered 'the standard' in the thermoelectric industry.

This broad product line of high-performance and highly reliable TEMs is available in numerous heat pumping capacities, geometric shapes, and input power ranges. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the CP Series is designed for higher current and large heat-pumping applications.

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### FEATURES

- Precise temperature control
- Compact geometric sizes
- Reliable solid state operation
- No sound or vibration
- Environmentally friendly
- DC operation
- RoHS compliant

### APPLICATIONS

- Medical lasers
- Lab science instrumentation
- Clinical diagnostics systems
- Photonics laser systems
- Electronic enclosure cooling
- Food & beverage cooling
- Chillers (liquid cooling)

### SPECIFICATIONS

| TECHNICAL                 |      |      |
|---------------------------|------|------|
| Hot Side Temperature (°C) | 25°C | 50°C |
| Qmax (Watts)              | 18.7 | 20.5 |
| Delta Tmax (°C)           | 67   | 75   |
| I <sub>max</sub> (Amps)   | 3.9  | 3.9  |
| V <sub>max</sub> (Volts)  | 8.6  | 9.2  |
| Module Resistance (Ohms)  | 1.92 | 2.17 |

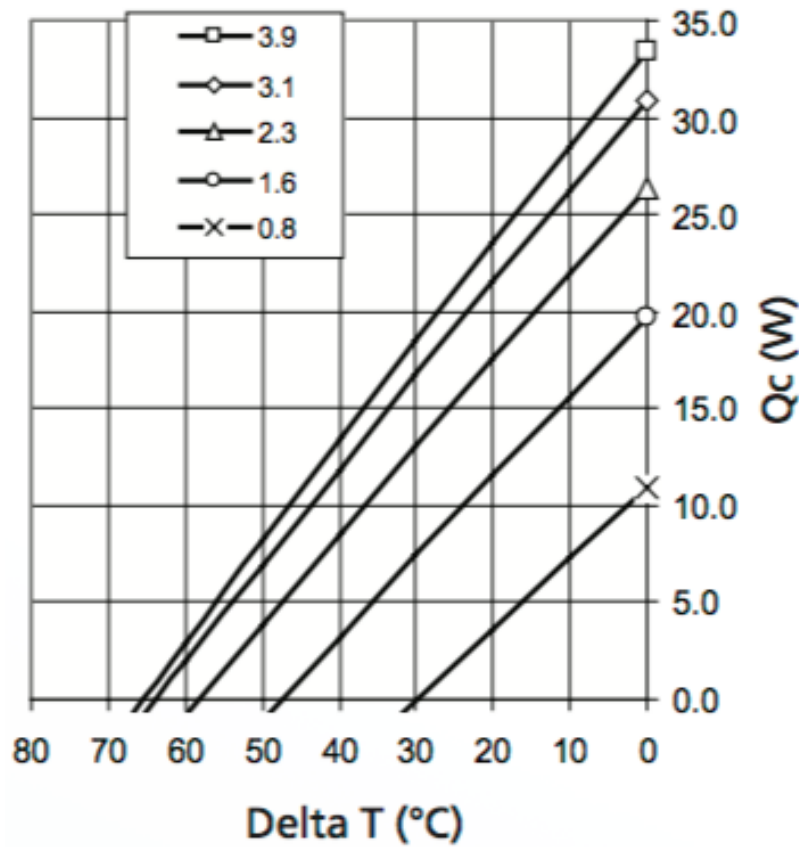
| SUFFIX | THICKNESS<br>(PRIOR TO<br>TINNING) | FLATNESS &<br>PARALLELISM | HOT FACE   | COLD FACE  | LEAD LENGTH |
|--------|------------------------------------|---------------------------|------------|------------|-------------|
| L      | 0.185"±0.010"                      | 0.002"/0.002"             | Lapped     | Lapped     | 4.5"        |
| L1     | 0.185"±0.001"                      | 0.001"/0.001"             | Lapped     | Lapped     | 4.5"        |
| L2     | 0.185"±0.0005"                     | 0.0005"/0.0005"           | Lapped     | Lapped     | 4.5"        |
| ML     | 0.189"±0.010"                      | 0.002"/0.002"             | Metallized | Lapped     | 4.5"        |
| LM     | 0.189"±0.010"                      | 0.002"/0.002"             | Lapped     | Metallized | 4.5"        |
| MM     | 0.193"±0.010"                      | 0.002"/0.002"             | Metallized | Metallized | 4.5"        |

### SEALING OPTIONS

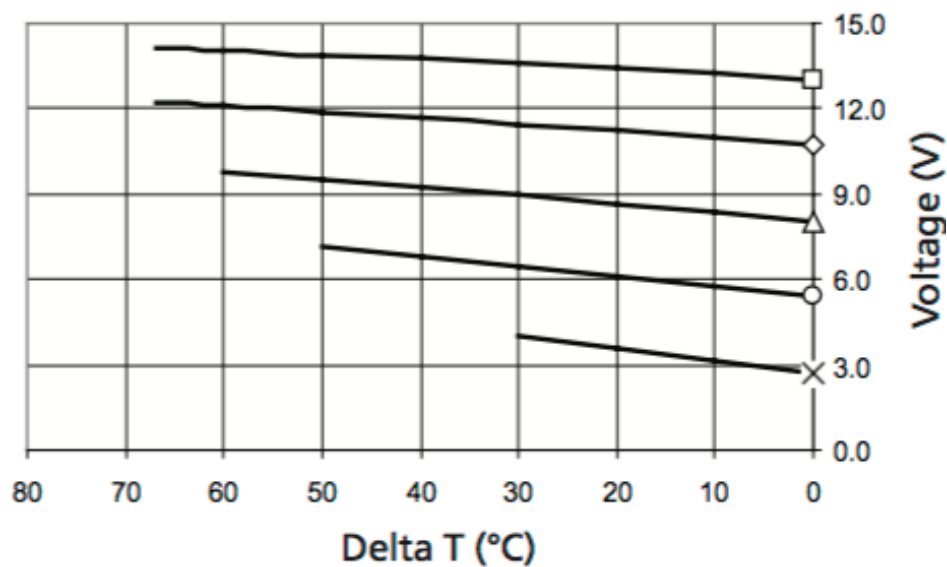
| SUFFIX | SEALANT | COLOR | TEMP RANGE    | DESCRIPTION                                  |
|--------|---------|-------|---------------|----------------------------------------------|
| RT     | RTV     | White | -60 to 204 °C | Non-corrosive, silicone adhesive             |
| EP     | Epoxy   | Black | -55 to 150 °C | Low density syntactic foam epoxy encapsulant |

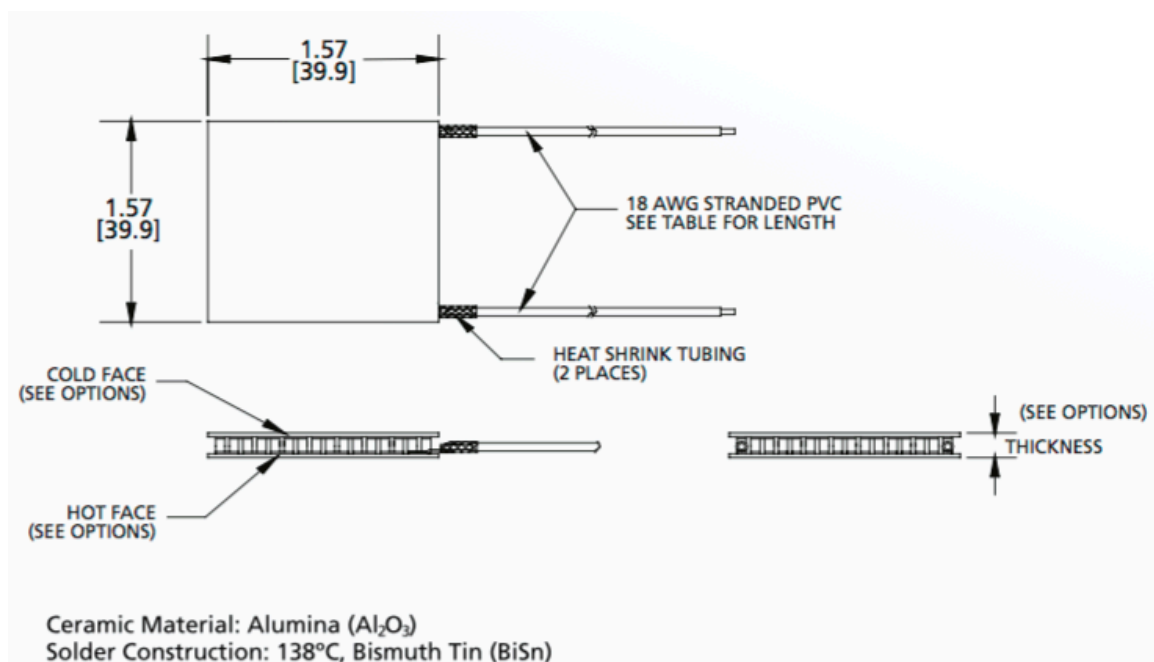
Performance Curves at  $T_h = 25^\circ\text{C}$

THERMO



ELECTRIC





## NOTES

1. Max operating temperature: 80°C
2. Do not exceed  $I_{\text{max}}$  or  $V_{\text{max}}$  when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

LAIRD-ETS-CP14-127-10-DATA-SHEET-101416

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